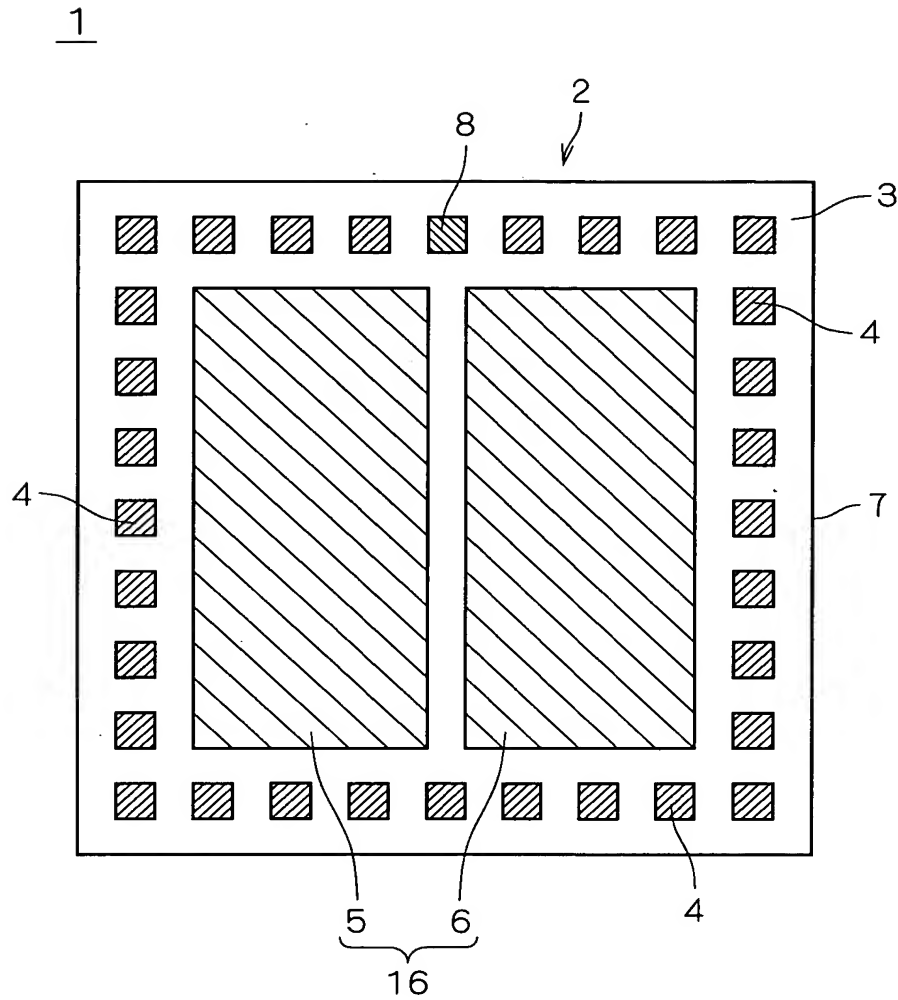


1 / 8

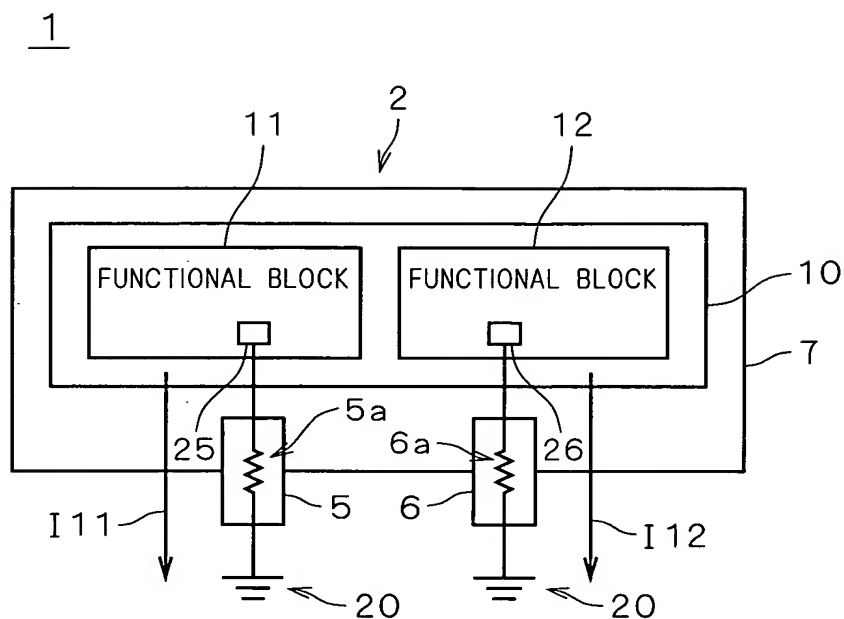
FIG. 1



- 1: SEMICONDUCTOR DEVICE  
2: PACKAGE  
3: MOLDING RESIN  
4: SIGNAL TERMINALS  
5, 6, 16: GROUND TERMINALS

2 / 8

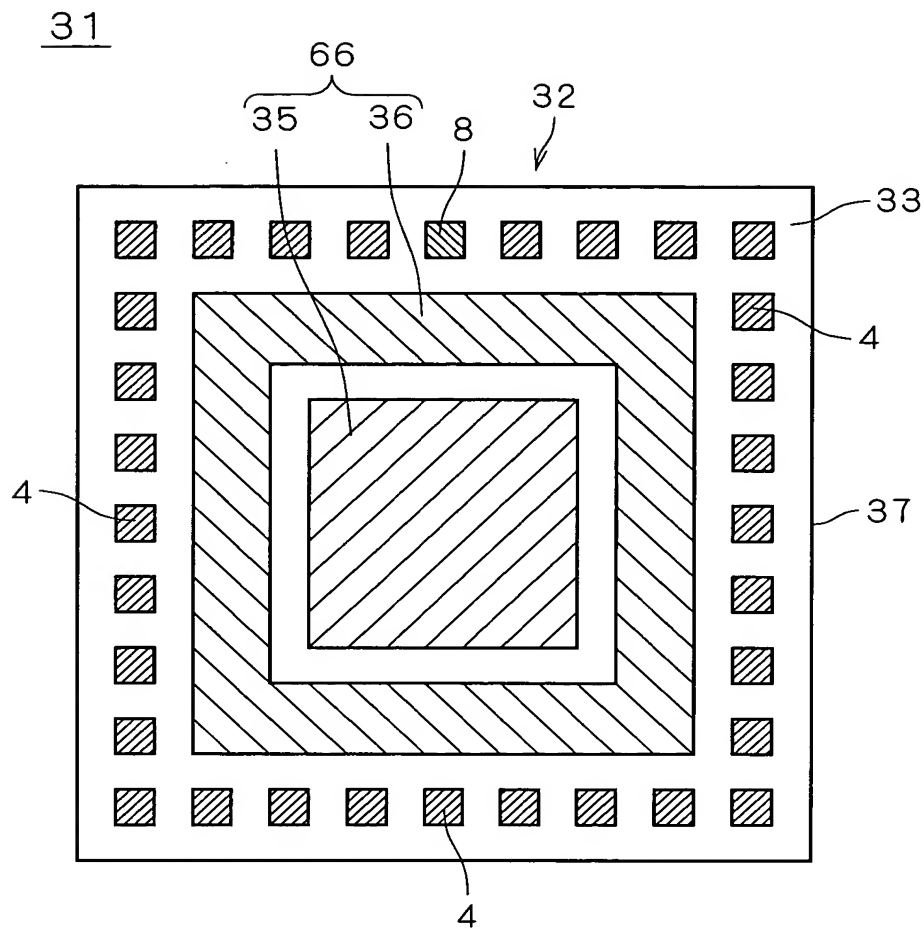
FIG. 2



10: SEMICONDUCTOR INTEGRATED CIRCUIT



F I G . 5



31: SEMICONDUCTOR DEVICE  
32: PACKAGE  
33: MOLDING RESIN  
35, 36, 66: GROUND TERMINALS

5 / 8

FIG. 6

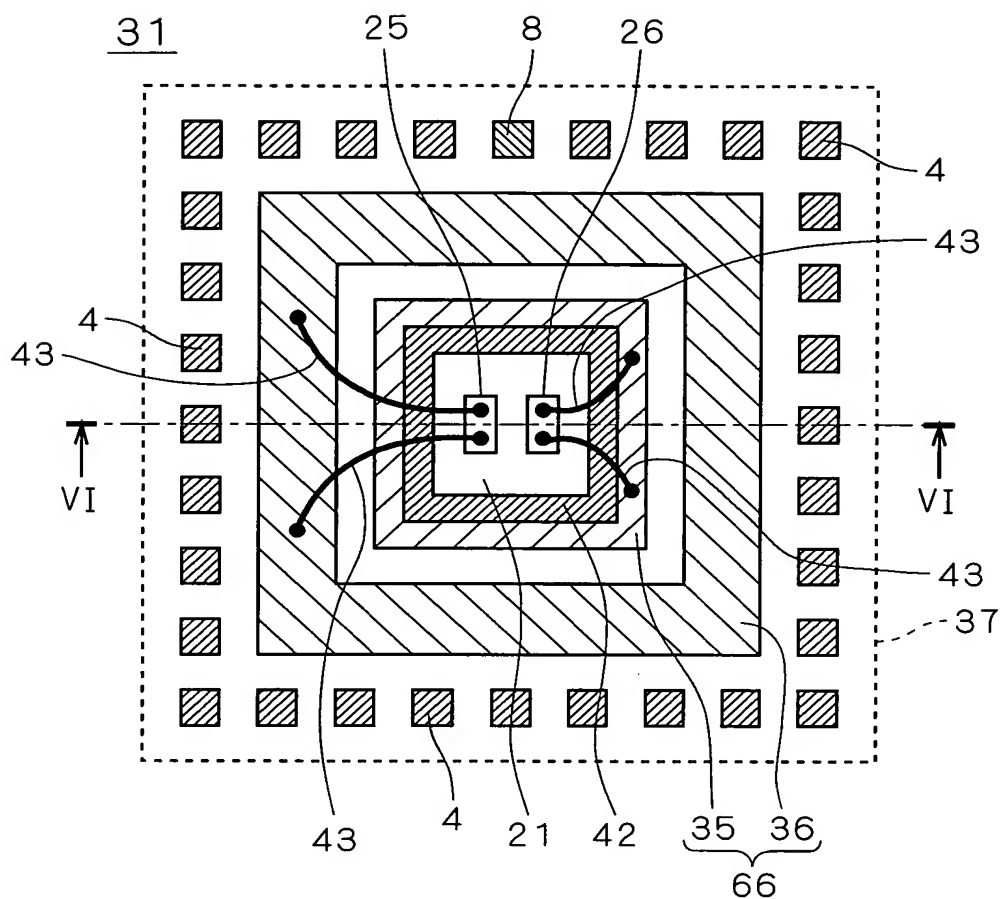
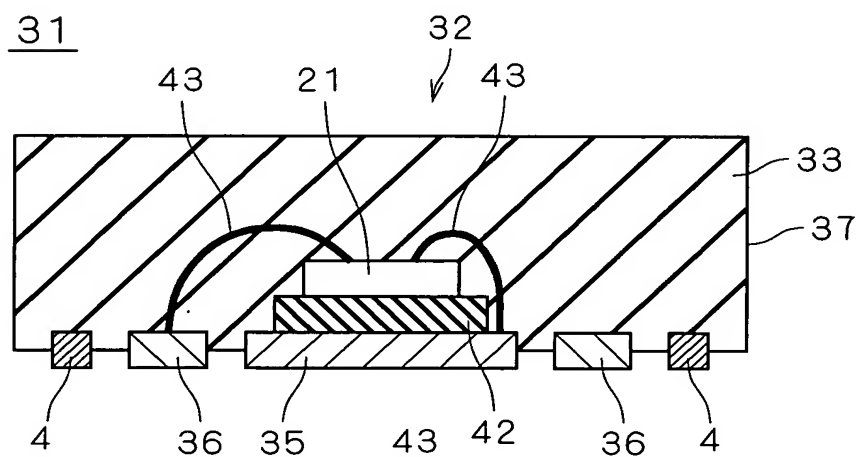
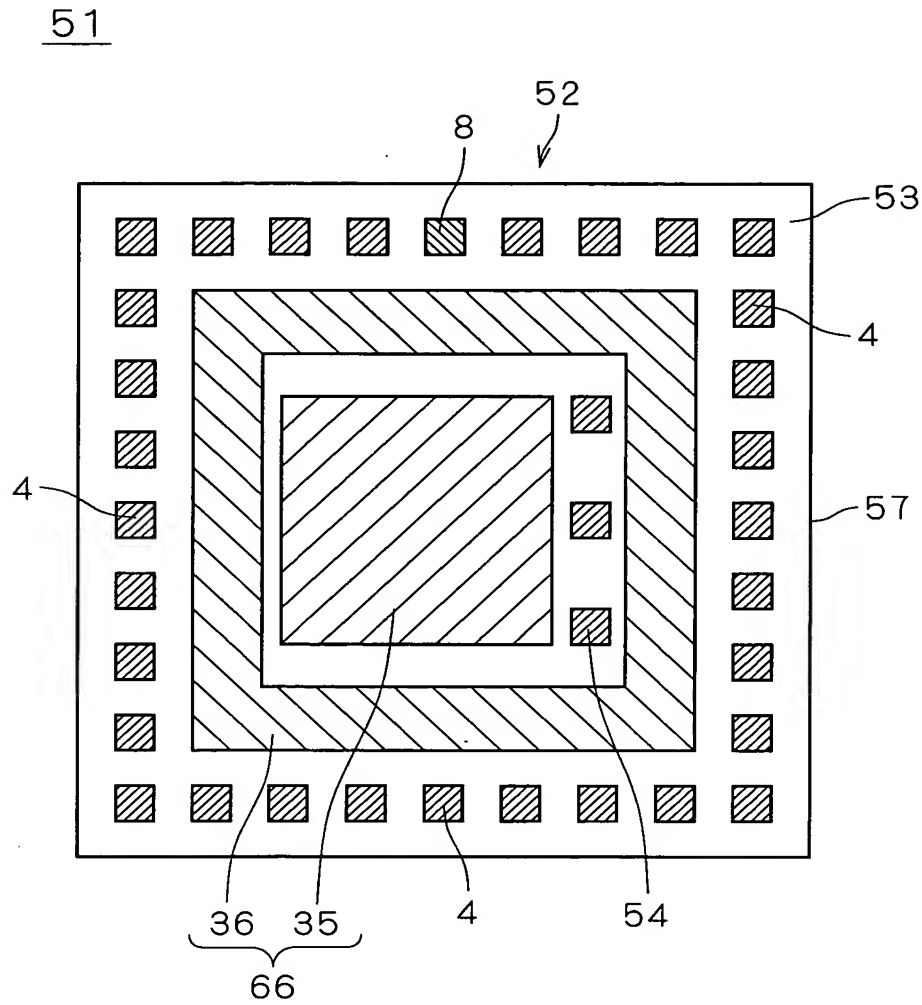


FIG. 7



6 / 8

FIG. 8



51: SEMICONDUCTOR DEVICE  
52: PACKAGE  
53: MOLDING RESIN  
54: SIGNAL TERMINALS

FIG. 9

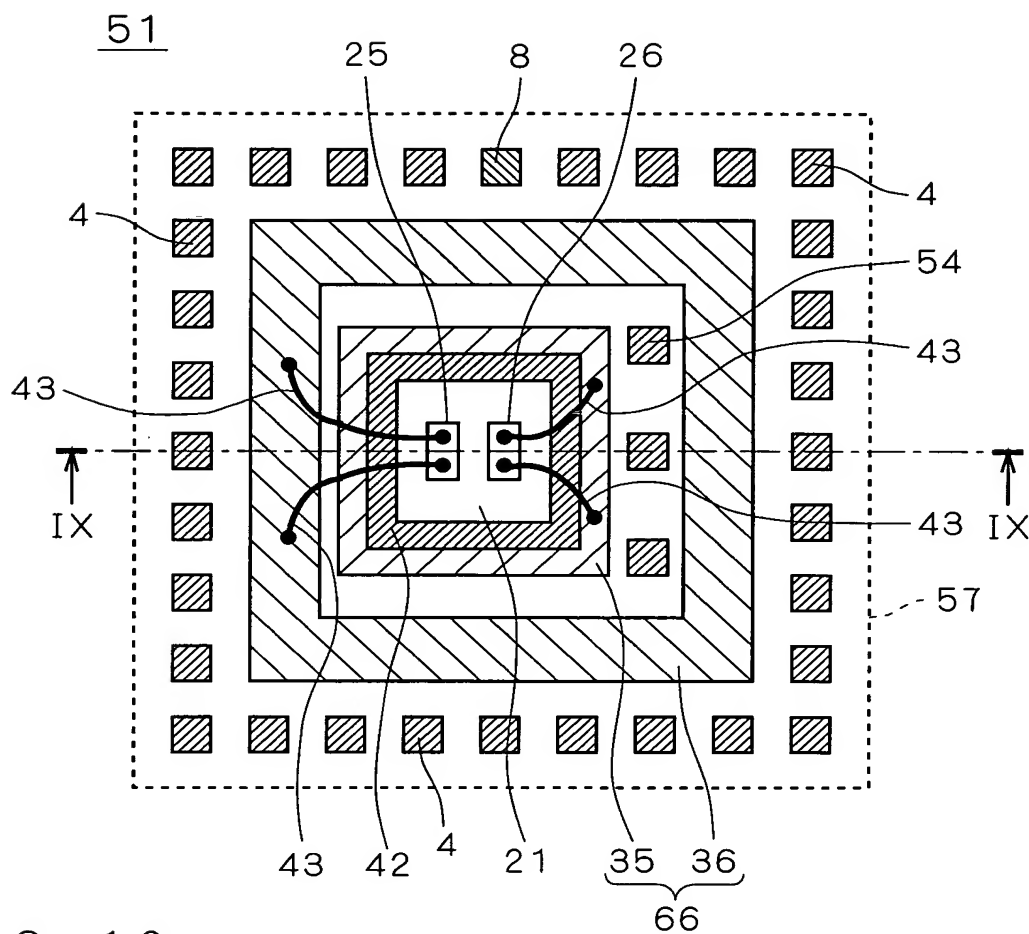
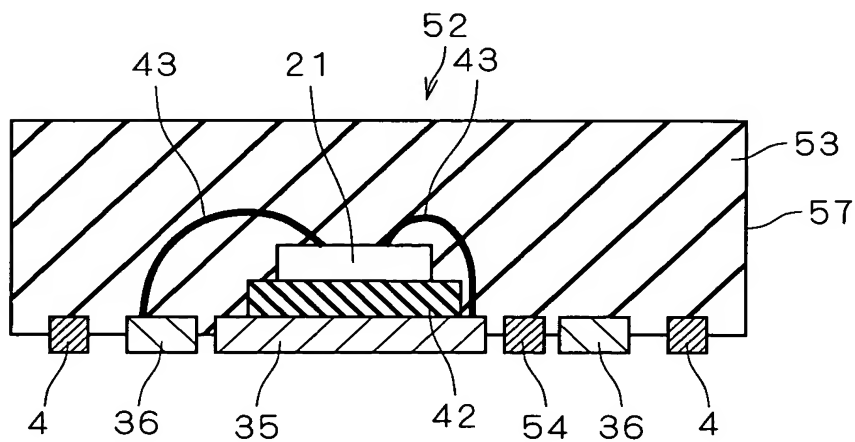


FIG. 10



8 / 8

FIG. 11

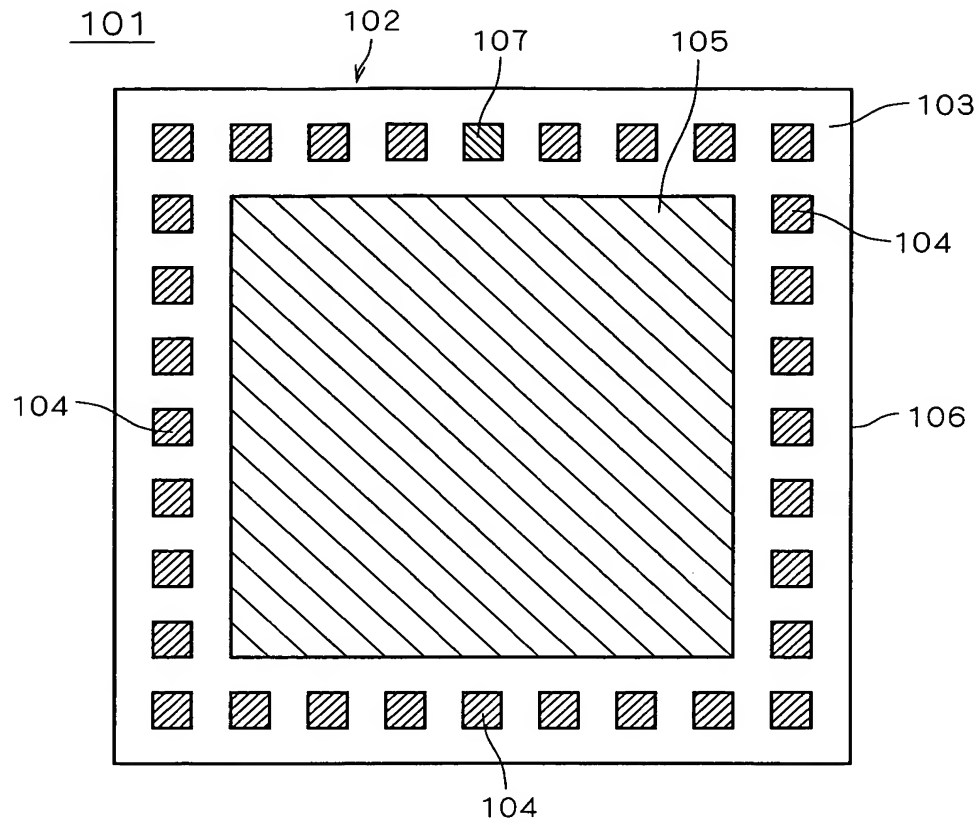


FIG. 12

